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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10030320	FILING DATE 12/22/2001	CLASS 448	SUBCLASS 51	GAU 1763	EXAMINER J. J. H. S.
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**CONTINUING DATA VERIFIED: THIS APPLICATION IS A 371 OF PCT/JP01/03632 04/26/2001					
** FOREIGN APPLICATIONS VERIFIED: JAPAN P2000-13195 04/28/2000					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO SOEI/0020	
TITLE : Wafer supporting device in semiconductor manufacturing device					
U.S. DEPT. OF COMM./PAT & TM-PTO-436L(Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Shots Drwg.	Figs. Drwg.
			Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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